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Radio Frequency. The global radio frequency integrated circuits (RFIC) market is anticipated to grow at around 8% CAGR through the period of 2021 to 2031, and reach a valuation of ...

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Radio Frequency Integrated Circuit Sales will rise at 8.0%
CAGR between 2021 and 2031

Display imaging processing semiconductor company Himax Technologies (NASDAQ: HIMX) stock has been a pandemic winner that will continue to flourish ...

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Since the second half of 2020, the global core shortage tide has made chip prices rise again and again, and the whole integrated circuit industry chain is surging. A senior executive of a domestic ...

The performance of the whole integrated circuit industry
chain is gratifying to take the lead in automobile IC design

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Total Telecom reports that China is steadily moving towards achieving its goal of mass-producing 14nm chips next year. According to Dr Wen Xiaojun, De ...

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That knowhow will allow chipmakers to stack integrated circuits on top of each other in a process called 3D packaging, promising smaller chip footprints, reduced power consumption and higher bandwidth ...

Eighty-year-old Japanese firm may be key to next-gen chip tech

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Next-gen chip tech could be unlocked with 3D packaging tools from 80-year-old Japanese company

The successful demonstration suggests that a next step would be adoption by industry for electronics packaging and incorporated into integrated circuits. “ Along with many others in the field, we have ...

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Eighty-year-old Japanese company may be key to next-generation chip technology

BANGKOK - Thailand has offered incentives to attract investment in the growing semiconductor, digital and packaging industries to meet ... said in a statement. Advanced integrated circuits, IC ...

Thailand offers perks to draw semiconductor, digital investments

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The company also provides Digital Light Processing (DLP) products for use in projectors to create HD images, calculators and application-specific integrated circuits. It sells its products through ...

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while advanced integrated circuits, integrated circuit substrate and printed circuit board projects with machinery investment of at least 1.5 billion baht will be offered an eight-year tax break.

Bol approves new R&D, HR privileges

KLA Corporation (NASDAQ: KLAC) today announced that the

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Company will review fourth quarter fiscal year 2021 earnings on Thursday, July 29, 2021 at 2 p.m. PT. The company's results will be published on ...

KLA Announces Fourth Quarter Fiscal Year 2021 Earnings Date

He will manage the company ' s portfolio of space products including applications-specific integrated circuits, radiation hardened microelectronics, advanced packaging platforms, positioning and ...

Mike Elias Named CAES Space Systems Division SVP, GM: Mike Kahn Quoted

In this role, Mike will oversee the company ' s space product

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portfolio including radiation hardened microelectronics, applications-specific integrated circuits (ASICs), advanced packaging ...

CAES Appoints Mike Elias as Senior Vice President and General Manager of Space Systems Division

That knowhow will allow chipmakers to stack integrated circuits on top of each other in a process called 3D packaging, promising smaller chip footprints, reduced power consumption and higher ...

Eighty-year-old Japanese firm may be key to next-gen chips
BANGKOK, June 30 (Reuters) - Thailand has offered incentives to attract investment in the growing

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circuits, IC (integrated circuit ...

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